

To: Facsimile Number: 703-872-9306

RECEIVED
CENTRAL FAX CENTER

Total Pages Sent 13

From:

Texas Instruments Incorporated
Facsimile: 972-917-4418

JUN 21 2005

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Applicant Young-Joon Park, et al.

Docket Number: TI-35623

Serial No.: 10/628,198

Art Unit: 2814

Filed: 07/28/03

Examiner: Ginette Peralta

For: A Two-Step Semiconductor Manufacturing Process for
Copper Interconnects

CERTIFICATION OF FACSIMILE TRANSMISSION

I hereby certify that the following papers are being transmitted by facsimile
to the U.S. Patent and Trademark Office on the date shown below:

Karen Vertz
Karen Vertz

6-21-05
Date

FACSIMILE COVER SHEET

<input checked="" type="checkbox"/> FACSIMILE COVER SHEET	<input checked="" type="checkbox"/> AMENDMENT <u>116 (11 pages)</u>
<input type="checkbox"/> NEW APPLICATION	<input checked="" type="checkbox"/> EOT <u>1 month</u>
<input type="checkbox"/> DECLARATION	<input type="checkbox"/> NOTICE OF APPEAL
<input type="checkbox"/> ASSIGNMENT	<input type="checkbox"/> APPEAL <u>(# Pages)</u>
<input type="checkbox"/> FORMAL DRAWINGS	<input type="checkbox"/> ISSUE FEE & PUBLICATION FEE (1 Page)
<input type="checkbox"/> INFORMAL DRAWINGS	<input type="checkbox"/> REPLY BRIEF (IN TRIPLICATE) (# Pages)
<input type="checkbox"/> CONTINUATION APP'N	<input type="checkbox"/> ELECTION
<input type="checkbox"/> DIVISIONAL APP'N	
NAME OF INVENTOR(S): Young-Joon Park, et al.	
TITLE OF INVENTION: A Two-Step Semiconductor Manufacturing Process for Copper Interconnects	
TI FILE NO.: TI-35623	DEPOSIT ACCT. NO.: 20-0668
FAXED: 6-21-05 DUE: 4-22-05 ATTY/SECY: RAK/kv	
RECEIPT DATE & SERIAL NO.: Serial No.: 10/628,198 Filing Date: 07/28/03	

This facsimile is intended only for the use of the address named and contains legally privileged and/or confidential information. If you are not the intended recipient of this telecopy, you are hereby notified that any dissemination, distribution, copying or use of this communication is strictly prohibited. Applicable privileges are not waived by virtue of the document having been transmitted by Facsimile. Any misdirected facsimiles should be returned to the sender by mail at the address indicated on this cover sheet.

Texas Instruments Incorporated
PO Box 655474, M/S 3999
Dallas, TX 75265-5474